AMENDMENTS TO THE CLAIMS

Please amend the claims as follows.

1. (Cancelled)

2. (Cancelled)

3. (Currently Amended) A support strip comprising:
at least one roughly parallel gripping area; and
~~at least one~~ a first support element and at least a second support element,
wherein the first support element comprises a first set of conducting elements, each of said conducting elements having a contact pad and a wiring pad,
wherein the second support element comprises a second set of conducting elements, each of said conducting elements having a contact pad and a wiring pad, and
wherein the first support element is connected to the at least one gripping area using at least a first snap-off junction area,
wherein the second support element is connected to the at least one gripping area using at least a second snap-off junction area, and
wherein ~~the first~~ each support element is configured to be overmoulded to obtain respectively a first and at least a second data carrier body.

4. (Previously Presented) The support strip according to claim 3, wherein the support element is a support grid.

5. (Currently Amended) The support strip according to claim 3, wherein the support element comprises a first set of foolproofing holes[[edge]].

6. (Currently Amended) The support strip according to claim [[4]]5, wherein the support element comprises a second set of foolproofing holes[[edge]].

7. (Currently Amended) The support strip according to claim [[3]] 4, wherein the support ~~element~~ grid is metallic.

8. (Currently Amended) The support strip according to claim [[4]] 3, wherein the first support element has a contour whose geometry substantially complies with ~~the standard~~ GSM 11.11.

9. (Original) The support strip according to claim 3, wherein the support element is arranged to receive an electronic component.

10. (New) The support strip according to claim 9, wherein the electronic component is a microcircuit.

11. (New) The support strip of according to claim 3, wherein the first support element is overmoulded using a thermoplastic.

12. (New) A support strip, comprising:

a first metal grid comprising a first set of contact pads and a first set of wiring pads;

at least a second metal grid comprising a second set of contact pads and second set of wiring pads;

wherein the first metal grid is connected to the support strip using at least a first snap-off junction,

wherein the second metal grid is connected to the support strip using at least a second snap-off junction, and

wherein each metal grid is configured to be overmoulded to obtain, respectively, a first and at least a second data carrier body.

13. (New) The support strip according to claim 12, wherein the support element comprises a first set of foolproofing holes.

14. (New) The support strip according to claim 13, wherein the support element comprises a second set of foolproofing holes.

15. (New) The support strip according to claim 12, wherein the first metal grid has a contour whose geometry substantially complies with GSM 11.11.

16. (New) The support strip according to claim 12, wherein the first metal grid is arranged to receive an electronic component.

17. (New) The support strip according to claim 16, wherein the electronic component is a microcircuit.

18. (New) The support strip according to claim 12, wherein the first metal grid is overmoulded using a thermoplastic.

19. (New) The support strip according to claim 3, wherein a microcircuit is connected to the wiring pad in the first set of conducting elements after the first support element has been overmoulded.

20. (New) The support strip according to claim 12, wherein a microcircuit is connected to the wiring pad in the first set of conducting elements after the first support element has been overmoulded.